ABSTRACT

DOUBLE PLASMA UTBOX

A method for bonding two substrates carried out in materials chosen from among semiconductor materials, said method implementing:

- A step to bond two substrates by thermal treatment;
- Plasma activation of the surface to be bonded for each substrate, the surfaces to be bonded of a first of the two substrates being comprised of an oxide layer,

The method characterized in that the plasma activation of said oxide layer is carried out under an atmosphere containing oxygen, and the plasma activation of the surface to be bonded of the second substrate is carried out under an inert atmosphere.

FIG. 1